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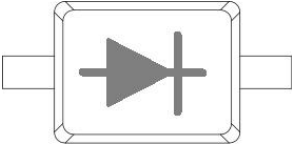


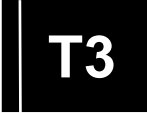
BAV19WS~BAV21WS

Product specification

FEATURES

- Low Reverse Current
- Surface Mount Package Ideally Suited for Automatic Insertion
- Fast Switching Speed
- For General Purpose Switching Applications

Reference News

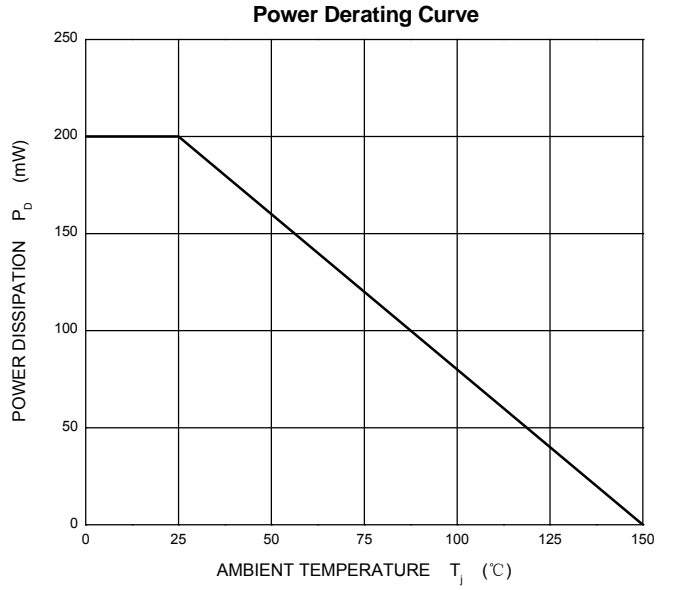
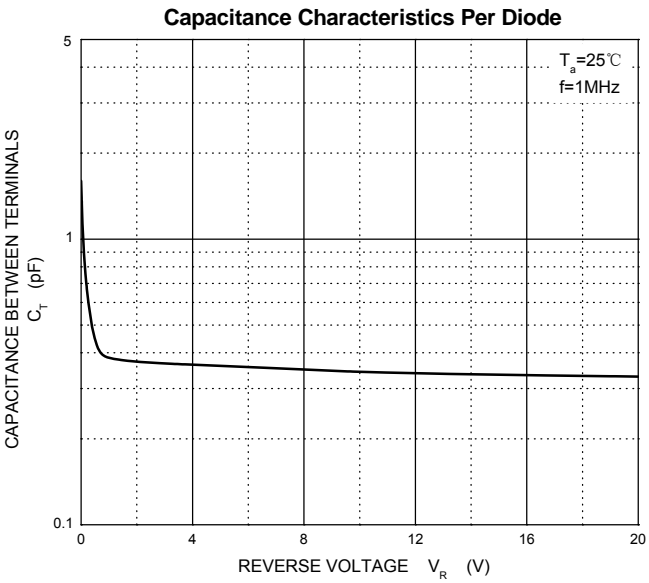
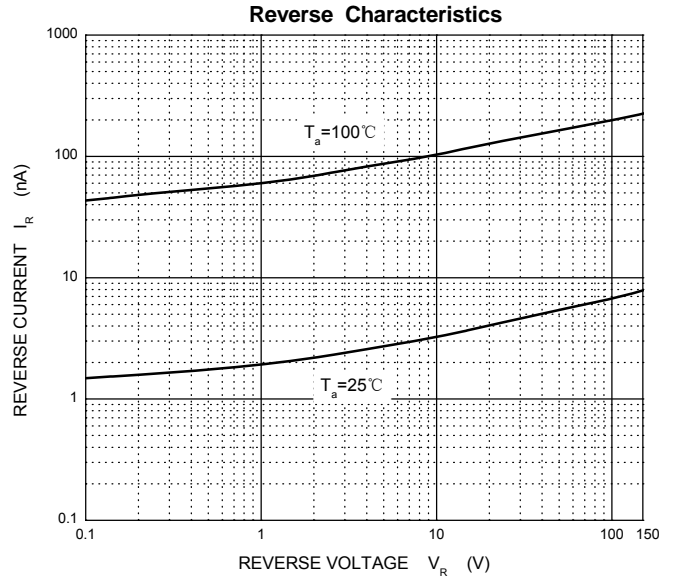
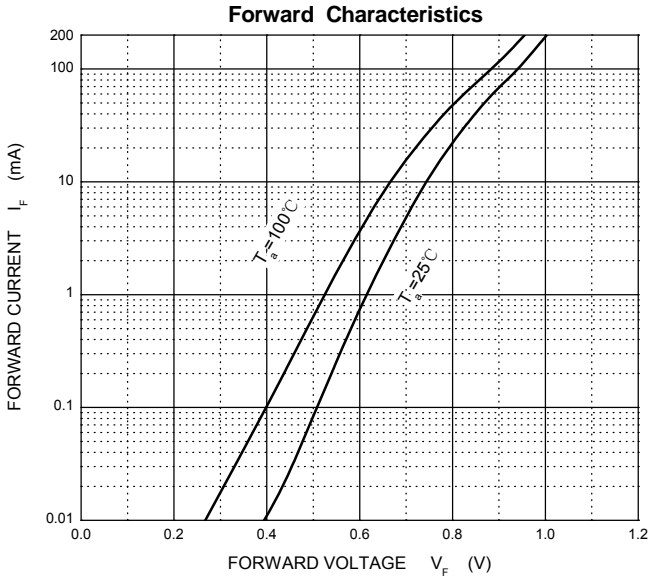
PACKAGE OUTLINE	PIN CONFIGURATION	BAV19WS	BAV20WS	BAV21WS
				
SOD-323		MARKING:A8	MARKING:T2	MARKING:T3

MAXIMUM RATINGS (Ta=25°C unless otherwise noted)

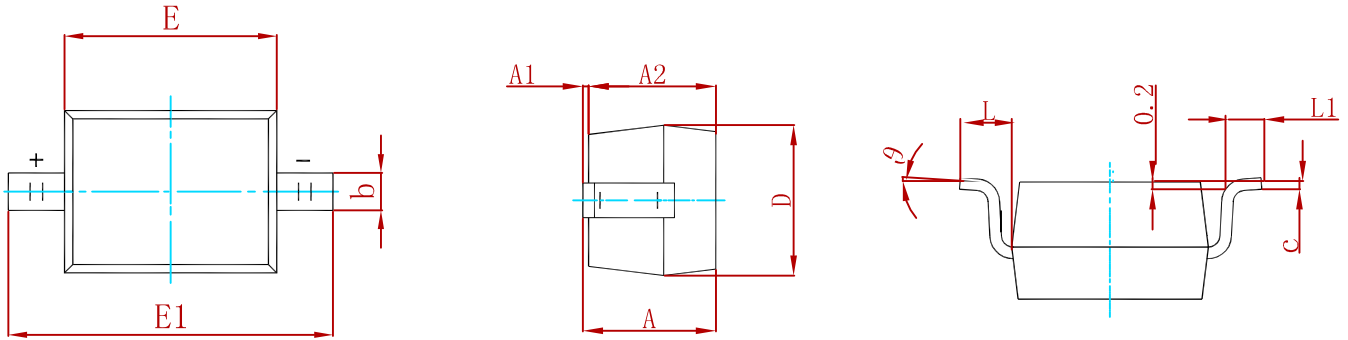
Symbol	Parameter	Value			Unit
		BAV19WS	BAV20WS	BAV21WS	
V_{RM}	Non-Repetitive Peak Reverse Voltage	120	200	250	V
V_{RRM}	Peak Repetitive Reverse Voltage	100	150	200	V
V_{RWM}	Working Peak Reverse Voltage				
$V_{R(RMS)}$	RMS Reverse Voltage	71	106	141	V
I_o	Average Rectified Output Current	200			mA
I_{FSM}	Non-repetitive Peak Forward Surge Current @ t=8.3ms	2.0			A
I_{FRM}	Repetitive Peak Forward Surge Current	625			mA
P_D	Power Dissipation	250			mW
R_{JA}	Thermal Resistance from Junction to Ambient	500			°C/W
T_J, T_{stg}	Operation Junction and Storage Temperature Range	-55~+150			°C

ELECTRICAL CHARACTERISTICS(Ta=25°C unless otherwise specified)

Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
Reverse current	IR	VR=100V	BAV19WS		0.1	uA
		VR=150V	BAV20WS		0.1	
		VR=200V	BAV21WS		0.1	
Forward voltage	VF	IF=100mA			1	V
		IF=200mA			1.25	
Total capacitance	Ctot	VR=0V,f=1MHz			5	pF
Reverse recovery time	trr	IF= IR =30mA, Irr=0.1*IR , RL=100Ω			50	ns

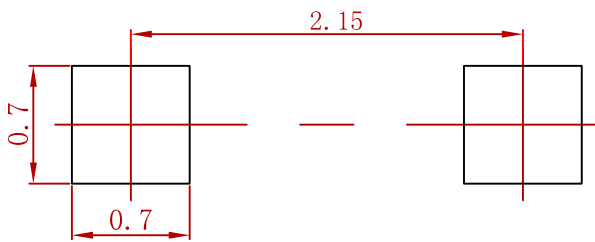


PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A		1.000		0.039
A1	0.000	0.100	0.000	0.004
A2	0.800	0.900	0.031	0.035
b	0.250	0.350	0.010	0.014
c	0.080	0.150	0.003	0.006
D	1.200	1.400	0.047	0.055
E	1.600	1.800	0.063	0.071
E1	2.550	2.750	0.100	0.108
L	0.475 REF.		0.019 REF.	
L1	0.250	0.400	0.010	0.016
θ	0°	8°	0°	8°

Suggested Pad Layout



- Note:**
1. Controlling dimension: in millimeters.
 2. General tolerance: ± 0.05 mm.
 3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
BAV19WS~BAV21WS	SOD-323	3000

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